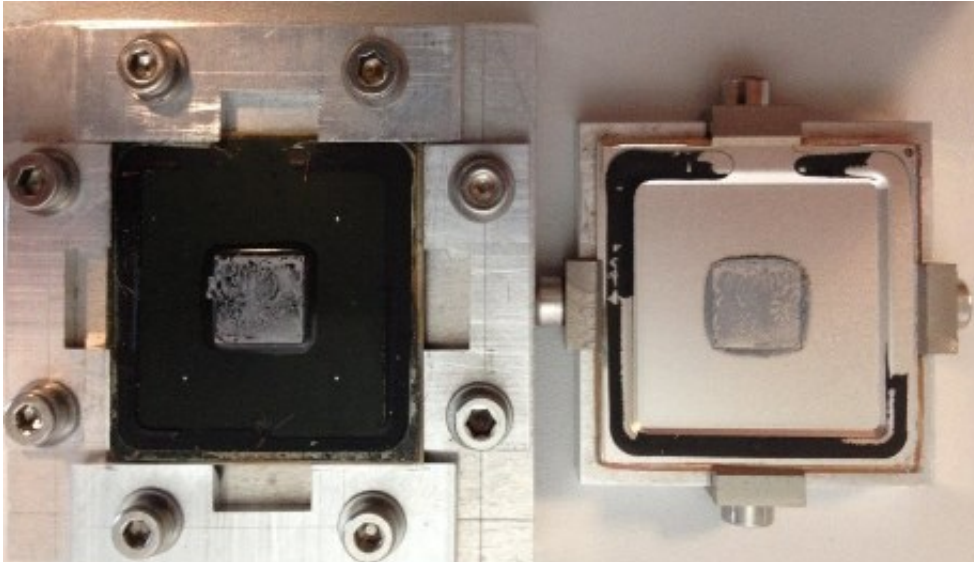




Newsletter: XYZTEC makes lid pull easy

30 September 2016

In this newsletter we describe a new method of testing the seal and adhesive quality of a lid encapsulated devices.



A new method of testing the seal and adhesive quality of a lid encapsulated devices - picture of both sides of the failed device

Typically this test is done by **stud pull** and gluing the lid and base of the device to two blocks of metal with screw holes in them that are used to apply the pull load. The disadvantages of this include;

- The cost of the disposable metal block/studs and adhesives.
- Handling of adhesives in the production environment with the risk of clean room contamination together with operator and equipment safety.
- Imprecise alignment of the studs to the device.

The new **XYZTEC mechanical grip method** consists of reusable parts that are accurately aligned the test load to the device. They can be quick release and in many cases handle a range of similar devices.

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XYZTEC Netherlands

J.F. Kennedylaan 14-B
5981 XC Panningen
Netherlands ([map / route](#))
Tel: +31-77-3060920
Fax: +31-77-3060919
sales@xyztec.com
support@xyztec.com

Other offices

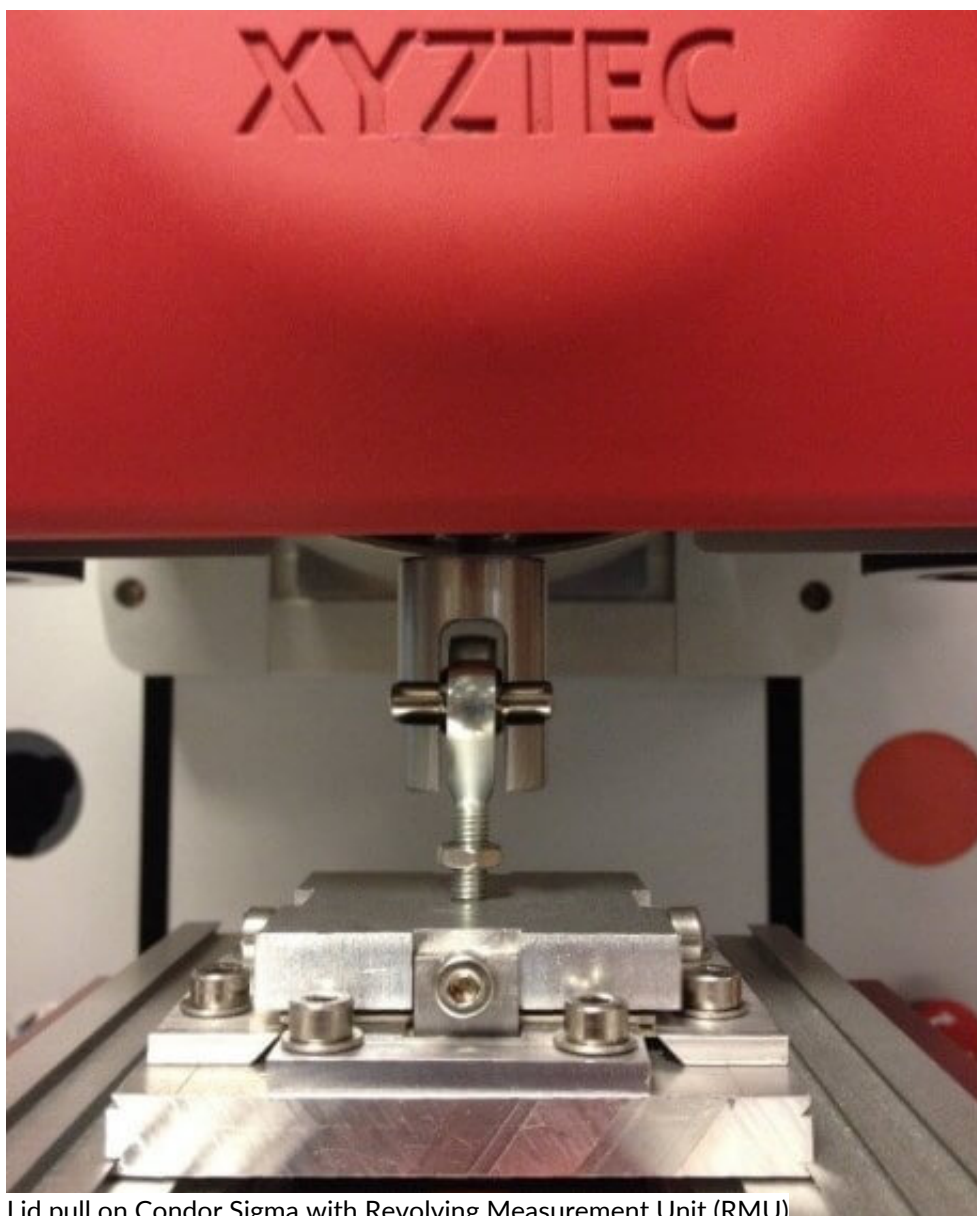
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Bond testers

- Condor *Sigma*
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- Condor *Sigma W12*
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Lid pull on Condor Sigma with Revolving Measurement Unit (RMU)

The lid and base of the device are gripped along their edges by side clamps.

The grippers can be screw fixed as is this example or quick release with a single lever operation. When the gap between the lid and its base is very small some sample preparation will probably be required. In such cases a bench mounted preparation jig can be provided.

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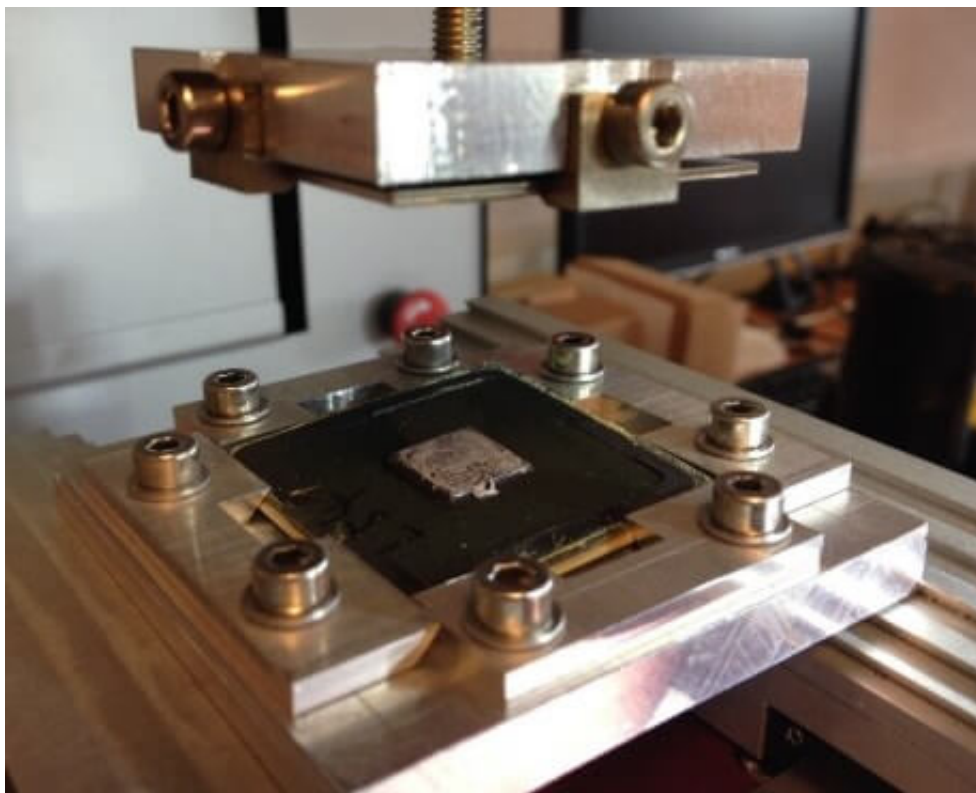
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The top and bottom parts of the have side grippers that respectively grab the lid and base

The bond can also easily be tested at elevated temperature by mounting either the lid clamp or base clamp onto a heated platform. See our extensive [range of work holders](#).

Learn more about the Condor Sigma

If you are interested in a live demonstration of the [Condor Sigma](#) on your sample or perhaps for more bond testing inspiration, [contact us today!](#) If you like our newsletter, feel free to share it with a friend or colleague.

About XYZTEC

XYZTEC manufactures and supports a complete range of bond test equipment for the printed circuit board assembly, semiconductor and other industries. The company was founded in 2000 and has seven direct offices around the world, with headquarters in Panningen, The Netherlands.

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Bond testing seminars

Aiming to improve understanding of bond testing in the industry, XYZTEC organizes [seminars](#) to present and disseminate knowledge in a straightforward format. [Click here to find out more about bond testing seminars.](#)

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